

Flex Manufacturing Capabilities

		Standard	Advanced (Limited Qty)
Material Types	1-2 layers	Polyimide, Dupont(AP,LF,FR)	Polyimide, Dupont(AP,LF,FR)
	3-6 layers	Polyimide, Dupont(AP,LF,FR)	Polyimide, Dupont(AP,LF,FR)
Material Thickness	1-2 Layers	.001 - .005"	.006"+ w/ special order
	3 Layers	.003 - .012"	.013"+
	4 Layers	.004 - .013"	.014"+
	6 Layers	.006 - .017"	.018"+
Layer Count		1-6	1-6
Max Board Size	2 layer	16.00 X 22.00"	16.00" X 22.00"
	Multilayer	16.00 X 22.00"	16.00" X 22.00"
Copper Weight	Outer Layer	.5 - 2 oz	3+ oz
	Inner Layer	.5 - 2 oz	3+ oz
Trace / Space (min)	Outer Layer	.004" / .004"	.003" / .003"
	Inner Layer	.004" / .004"	.003" / .003"
PCB Edge to Conductor Min		.015"	.010"
Minimum Dielectric Thickness		.001"	.001"
Smallest Drilled Via		.010"	.008"
Outer Via Pad Min.		.026"	.020"
Inner Via Pad Min.		.026"	.020"
Inner Layer Clearance Min.		.038"	.030"
PTH Tolerance Finished		+/- .003"	+/- .002"
Max Aspect Ratio		1:1	1:1
Plated Slots Min		.030"	.020"
Plated Features		Bump Pads, Pattern Plate	
Surface Finishes		ENIG, Immersion Tin	ENIG, Immersion Tin, HASL, Silver
Covercoat w/ Adhesive		Dupont(LF,FR) .002"+	
Soldermask Color		Flex LPI: Green	
Soldermask Dam (min)		.005"	.003"
Soldermask Clearance (min)		.004"	.002"
Legend Colors		White, Yellow, Black, Red, Blue	
Controlled Impedance + / -		10 %	10 %
SMT Pitch for Electrical Test		.012"	.008"
Min Rout Width		.062"	.031"
IPC Class		Class II	Class III

Additional Offerings		
Rigid / Flex (up to 10 layers)	.030-.200"	130 - 180Tg , Poyimide, FR4, AP, LF, FR
LPI Covercoat		Dupont PC (Photoimageable Covercoat)
Stiffeners		.003 - .125 FR4, Polyimide, Kapton
Epoxy Fillet @ Bend		Ecobond 45 (Clear , Black)
Pressure Sensitive Tape		3M 467MP / 200MP Adhesive
Flex LPI w/ Covercoat		Taiyo Flex LPI w/ Dupont (LF, FR)
Skiving / Flying Leads		Laser Ablation of substrate to create windows or expose leads